

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







30V Nch+Nch Middle Power MOSFET

V_{DSS}	30V
R _{DS(on)} (Max.)	42mΩ
I _D	±5.5A
P _D	2W

Features

- 1) Low on resistance.
- 2) Small Surface Mount Package .
- 3) Pb-free lead plating; RoHS compliant.
- 4) Halogen Free.

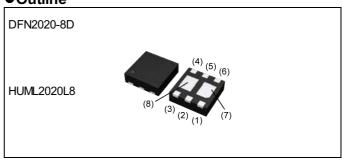
Application

Load Switch

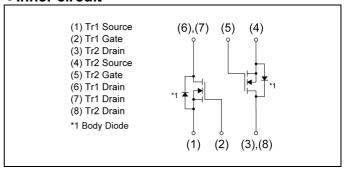
Battery Switch for mobile

DC/DC Converter

Outline



•Inner circuit



Packaging specifications

UI ackaç	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	180
Type	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	K03

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	30	V
Continuous drain current	I _D	±5.5	А
Pulsed drain current	I _{DP} *1	±12	А
Gate - Source voltage	V _{GSS}	±12	V
Avalanche current, single pulse	I _{AS} *2	5.5	Α
Avalanche energy, single pulse	E _{AS} *2	2.4	mJ
Power dissipation	P _D *3	2	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Davamatav	Symbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJA} *3	1	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Danamatan	Cumphal	0 - 1141 - 11 -	Values			I India
Parameter	Symbol	Conditions	Min.			Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	18	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V	-	-	1	μA
Gate - Source leakage current	I _{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$	1	-	±100	nA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	0.5	-	1.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{\text{GS(th)}}}{\DeltaT_j}$	I _D = 1mA referenced to 25°C	-	-1.8	-	mV/°C
Static drain - source	D *4	V _{GS} = 4.5V, I _D = 5.0A	-	30	42	mO.
on - state resistance	R _{DS(on)} *4	V _{GS} = 2.5V, I _D = 2.75A	-	45	63	mΩ
Gate resistance	R_G	f=1MHz, open drain	ı	2.2	-	Ω
Forward Transfer Admittance	Y _{fs} *4	$V_{DS} = 5.0V, I_{D} = 5.0A$	2.3	-	-	S

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} L $^{\sim}$ 0.1mH, V_{DD} = 15V, R_G = 25 Ω , STARTING T $_{j}$ = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a Cu boad (40×40×0.8mm)

^{*4} Pulsed

ullet Electrical characteristics (T_a = 25°C) <Tr1 and Tr2>

Daramatar	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	450	-	_
Output capacitance	C _{oss}	V _{DS} = 15V	-	50	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	1	35	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 15V, V_{GS} = 4.5V$	1	7.2	-	
Rise time	t _r *4	I _D = 2.75A	1	5.8	-	no
Turn - off delay time	t _{d(off)} *4	$R_L = 6\Omega$		13	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	5.1	-	

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	mbol Conditions		Тур.	Max.	Offic
Total gate charge	Q_g^{*4}		-	4.0	-	
Gate - Source charge	Q _{gs} *4	$V_{DD} \approx 15V, I_{D} = 5.5A$ $V_{GS} = 4.5V$	-	1.0	-	nC
Gate - Drain charge	Q _{gd} *4	1.63	-	1.0	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
raianetei	Symbol Conditions		Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T _a = 25°C	-	-	1.6	А	
Pulse forward current	I _{SP} *1		-	-	12		
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = 1.6A$	-	ı	1.2	V	

Fig.1 Power Dissipation Derating Curve

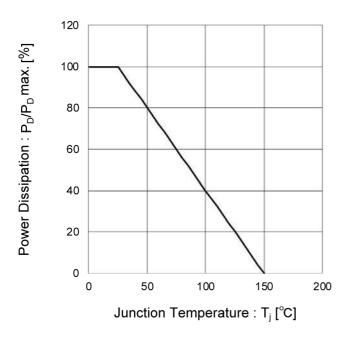
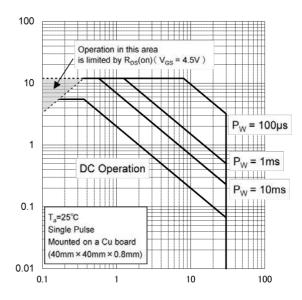


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

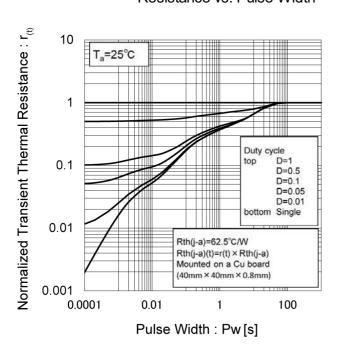
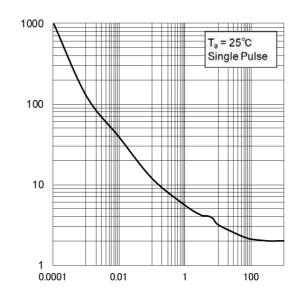


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Peak Transient Power: P(W)

Fig.5 Typical Output Characteristics(I)

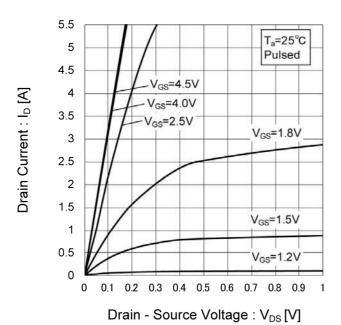
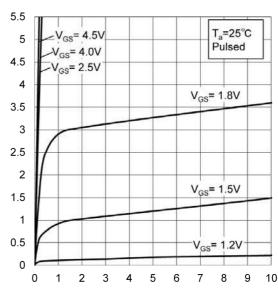


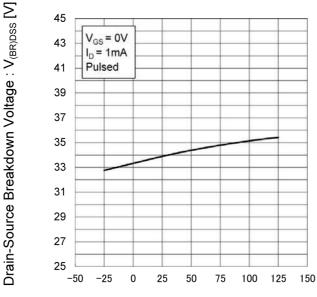
Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

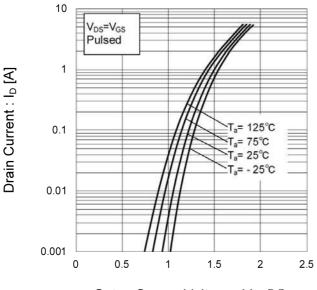
Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

Fig.9 Gate Threshold Voltage vs. Junction Temperature

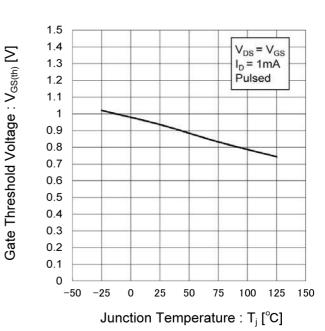
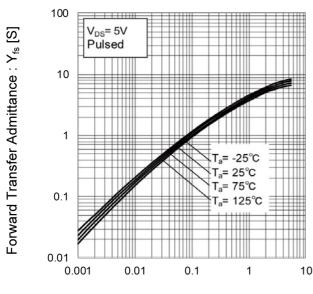


Fig.10 Forward Transfer Admittance vs. Drain Current



Drain Current: ID [A]

Fig.11 Drain Current Derating Curve

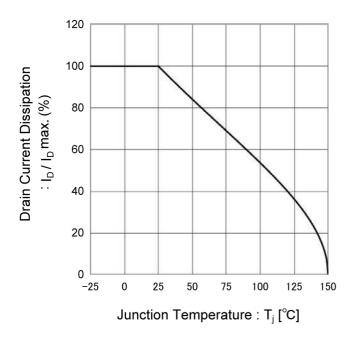


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

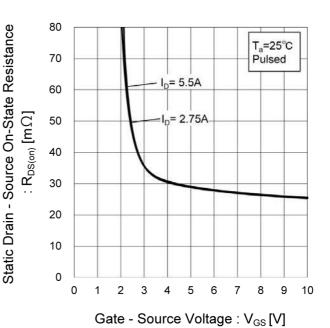
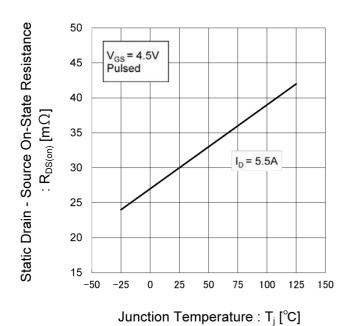


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



ROHM

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

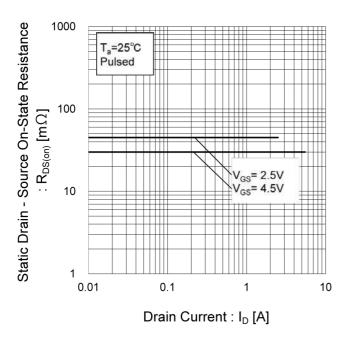


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

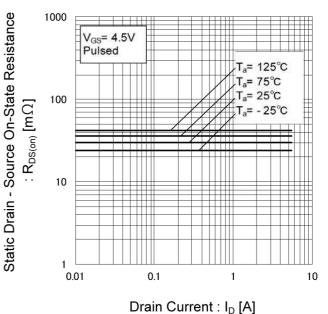


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

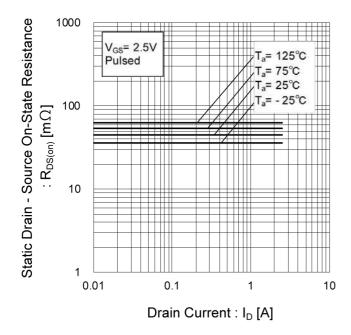
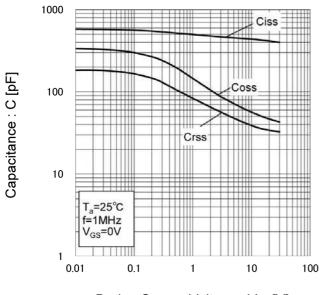
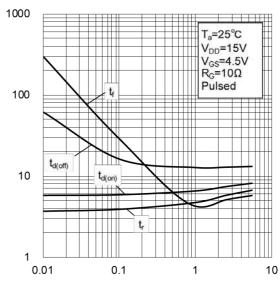


Fig.17 Typical Capacitance vs. Drain - Source Voltage



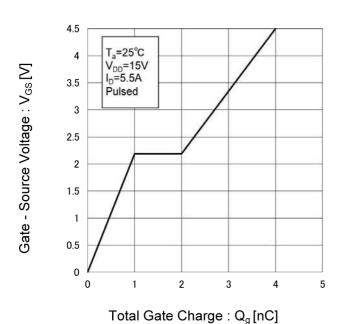
Drain - Source Voltage : $V_{DS}[V]$

Fig.18 Switching Characteristics



Drain Current : I_D [A]

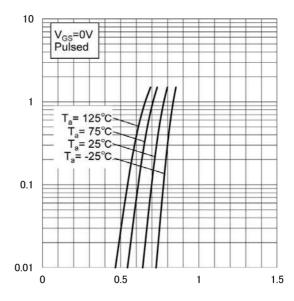
Fig.19 Dynamic Input Characteristics



Source Current :I_S [A]

Switching Time : t [ns]

Fig.20 Source Current vs. Source Drain Voltage



Source-Drain Voltage: V_{SD}[V]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

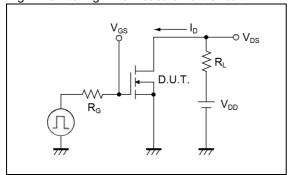


Fig.2-1 Gate Charge Measurement Circuit

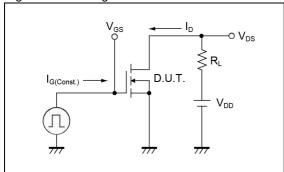


Fig.3-1 Avalanche Measurement Circuit

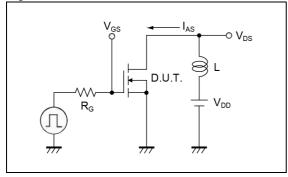


Fig.1-2 Switching Waveforms

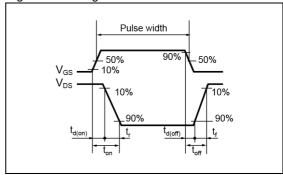


Fig.2-2 Gate Charge Waveform

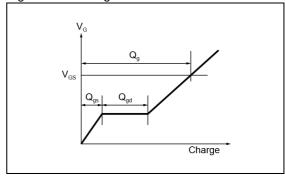
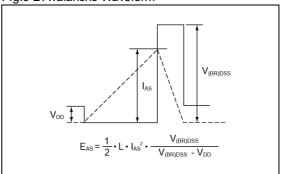


Fig.3-2 Avalanche Waveform

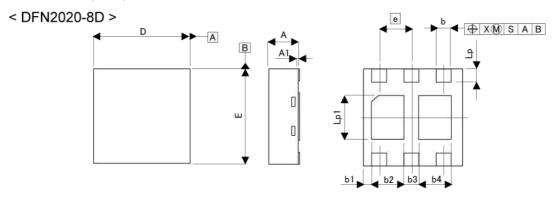


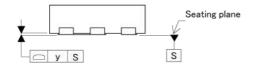
Notice

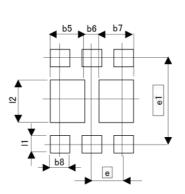
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

HUML2020L8 (Dual)







Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.55	0.65	0.022	0.026
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
b1	0.:	25	0.0	010
b2	0.60	0.70	0.024	0.028
b3	0	.3	0.0)12
b4	0.60	0.70	0.024	0.028
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
е	0.0	65	0.0	26
Lp	0.225	0.325	0.009	0.013
Lp1	0.80	1.00	0.031	0.039
x	-	0.10	3 + 3	0.004
٧	-	0.10	958	0.004

DIM	MILIME	MILIMETERS		HES
DIIVI	MIN	MAX	MIN	MAX
b5	-	0.70	3.83	0.028
b6	0.20	0.30	0.008	0.012
b7	-	0.70) + (0.028
b8	-	0.45		0.018
e1	1.7	725	0.0	68
11	-	0.425	1050	0.017
12	-	1.00	581	0.039

Dimension in mm/inches



Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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QR code printed on ROHM Products label is for ROHM's internal use only.

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- 3. The information contained in this doc ument is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

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UT6K3 - Web Page

Distribution Inventory

Part Number	UT6K3
Package	HUML2020L8(Dual)
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes